

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Michael S. Leung et al.

Confirmation No.: 8955

Serial No.: 10/666,399

Examiner: Abul Kalam

Filed: September 18, 2003

Art Unit: 2814

Title: MOLDED CHIP FABRICATION METHOD

Notice of Allowance Date: October 14, 2010

Mail Stop Issue Fee  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450


**COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE**

Sir:

Applicants agree that the Examiner has accurately stated one or more reasons for allowance of the claims. However, the claims may include other patentable aspects that were not identified by the Examiner. This response is submitted to avoid the possibility of any unnecessary limitation on the scope of the claims which might result from the stated reason for allowance. It is being submitted concurrently with the issue fee payment.

Respectfully submitted,

Dated: 1/10/11

  
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J\11\PO298US-7\011011\ReasonsForAllowance

CERTIFICATE OF ELECTRONIC FILING

I hereby certify that this correspondence is being deposited with the United States Patent & Trademark office via Electronic Filing through the United States Patent and Trademark Office e-business website, on the date shown below.

1/10/11  
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Joan Harriman